

SCDS198C-OCTOBER 2005-REVISED MAY 2006

FEATURES

•	Compatible With HDMI v1.2a (Type A) DVI 1.0 High-Speed Digital Interface – Wide Bandwidth of Over 1.65 Gbps (Bandwidth 1.8 Gbps Typ) – 165-MHz Speed Operation – Serial Data Stream at 10× Pixel Clock Rate		V PACKAGE VIEW) 48 0B ₁ 47 1B ₁ 46 GND
	 Supports All Video Formats up to 1080p and SXGA (1280 × 1024 at 75 Hz) 	A ₁ 4 GND 5 V _{DD} 6	45 0B ₂ 44 1B ₂ 43 GND
	 Total Raw Capacity 4.95 Gbps (Single Link) HDCP Compatible 	GND [] 7 A ₂ [] 8	42 2B ₁ 41 3B ₁
٠	Low Crosstalk (X _{TALK} = –41 dB Typ)	GND 9	40 GND
٠	Low Bit-to-Bit Skew (t _{sk(o)} = 0.2 ns Max)	A ₃ 10	39 2B ₂
٠	Low and Flat ON-State Resistance	GND 11	383B ₂
	(r_{on} = 4 Ω Typ, $r_{on(flat)}$ = 0.7 Ω Typ)		37 GND
٠	Low Input/Output Capacitance	GND [] 13	36 V _{DD}
	(C _{ON} = 10 pF Typ)	NC L 14 A4 L 15	35
•	Rail-to-Rail Switching on Data I/O Ports (0 to 5 V) V _{DD} Operating Range From 3 V to 3.6 V I _{off} Supports Partial-Power-Down Mode	A ₄ L 15 GND L 16	33 GND
•	V _{DD} Operating Range From 3 V to 3.6 V	A ₅ 17 GND 18	32 4B ₂ 31 5B ₂
•	I _{off} Supports Partial-Power-Down Mode		30 GND
	Operation		29 6B1
•	Latch-Up Performance Exceeds 100 mA Per	$A_6 \begin{bmatrix} 21 \\ 21 \end{bmatrix}$	28 7B1
	JESD 78, Class II	GND 22	27 GND
•	ESD Performance Tested Per JESD 22	A ₇ 🛛 23	26 6B ₂
	– 2000-V Human-Body Model	SEL 🛛 24	25 7B ₂
	(A114-B, Class II) – 1000-V Charged-Device Model (C101)	NC – No in	ternal connection

APPLICATIONS

- Digital Video Signal Switching
- Differential DVI, HDMI Signal Multiplexing for Audio/Video Receivers and High-Definition Television (HDTV)

DESCRIPTION/ORDERING INFORMATION

The TS3DV416 is a 16-bit to 8-bit multiplexer/demultiplexer digital video switch with a single select (SEL) input. SEL controls the data path of the multiplexer/demultiplexer.

The device provides a low and flat ON-state resistance (r_{on}) and an excellent ON-state resistance match. Low input/output capacitance, high bandwidth, low skew, and low crosstalk among channels make this device suitable for various digital video applications, such as DVI and HDMI.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

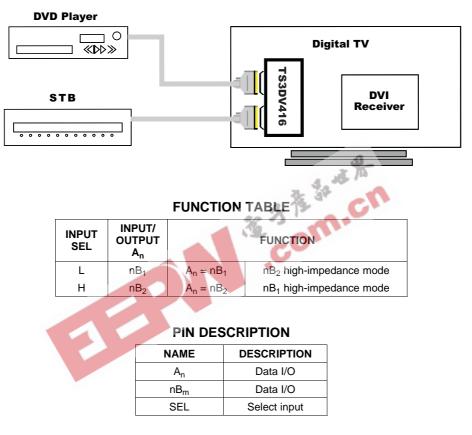


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ORDERING INFORMATION

T _A	PACK	AGE ⁽¹⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING		
–40°C to 85°C	TSSOP – DGG	Tape and reel	TS3DV416DGGR	TS3DV416		
-40°C 10 85°C	TVSOP – DGV	Tape and reel	TS3DV416DGVR	SD416		

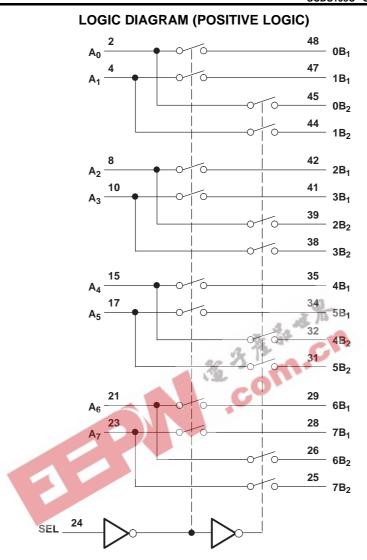
(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



TYPICAL APPLICATION

TEXAS INSTRUMENTS www.ti.com

TS3DV416 4-CHANNEL DIFFERENTIAL 8:16 MULTIPLEXER SWITCH FOR DVI/HDMI APPLICATIONS SCDS198C-OCTOBER 2005-REVISED MAY 2006





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Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{DD}	Supply voltage range	-0.5	4.6	V	
V _{IN}	Control input voltage range ⁽²⁾⁽³⁾		-0.5	7	V
V _{I/O}	Switch I/O voltage range ⁽²⁾⁽³⁾⁽⁴⁾		-0.5	7	V
I _{IK}	Control input clamp current	V _{IN} < 0		-50	mA
I _{I/OK}	I/O port clamp current	V _{I/O} < 0		-50	mA
I _{I/O}	ON-state switch current ⁽⁵⁾			±128	mA
	Continuous current through V _{DD} or GND			±100	mA
0	Deckage thermal impedance (6)	DGG package		70	°C/W
θ_{JA}	Package thermal impedance ⁽⁶⁾	DGV package		58	-C/W
T _{stg}	Storage temperature range		-65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2)All voltages are with respect to ground, unless otherwise specified.

- (3) The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- $V_{\rm I}$ and $V_{\rm O}$ are used to denote specific conditions for $V_{\rm I/O}.$ (4)

(i) v₁ and v₀ are used to denote specific conditions for V_{1/0}. (j) I₁ and I₀ are used to denote specific conditions for I_{1/0}. (e) The package thermal impedance is calculated in accordance with JESD 51-7. Recommended Operating Conditions⁽¹⁾

			C	MIN	MAX	UNIT
V_{DD}	Supply voltage	<u>``</u>		3	3.6	V
V _{IH}	High-level control input voltage (SEL)			2	5.5	V
V _{IL}	Low-level control input voltage (SEL)			0	0.8	V
V _{I/o}	Input/output voltage			0	5.5	V
T _A	Operating free-air temperature			-40	85	°C

(1) All unused inputs of the device must be held at V_{DD} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



Electrical Characteristics⁽¹⁾

for high-frequency switching over recommended operating free-air temperature range, V_{DD} = 3.3 V \pm 0.3 V (unless otherwise noted)

PARA	METER		TEST CO	MIN	TYP ⁽²⁾	MAX	UNIT		
V _{IK}	SEL	V _{DD} = 3.6 V,	I _{IN} = -18 mA				-0.7	-1.2	V
I _{IH}	SEL	V _{DD} = 3.6 V,	$V_{IN} = V_{DD}$					±1	μA
IIL	SEL	V _{DD} = 3.6 V,	V _{IN} = GND					±1	μA
I _{off}		$V_{DD} = 0,$	$V_0 = 0$ to 3.6 V,	V ₁ = 0				1	μA
I _{DD}		V _{DD} = 3.6 V,	$I_{I/O} = 0,$	Switch ON or OFF			250	600	μA
C _{IN}	SEL	f = 1 MHz,	$V_{IN} = 0$				2.5	3	pF
C _{OFF}	B port	$V_I = 0,$	f = 1 MHz,	Outputs open,	Switch OFF		3.5	4	pF
C _{ON}		$V_{I} = 0,$	f = 1 MHz,	Outputs open,	Switch ON		10	10.9	pF
r _{on}		$V_{DD} = 3 V,$	$1.5~V \leq V_I \leq V_{DD},$	$I_0 = -40 \text{ mA}$			4	8	Ω
r _{on(flat)} ⁽³⁾		V _{DD} = 3 V,	$V_I = 1.5 V \text{ and } V_{DD},$	I _O = -40 mA			0.7		Ω
$\Delta r_{on}^{(4)}$		V _{DD} = 3 V,	$1.5 \text{ V} \leq \text{V}_{\text{I}} \leq \text{V}_{\text{DD}},$	I _O = -40 mA			0.2	1.2	Ω

 $\begin{array}{ll} (1) & V_{I}, \, V_{O}, \, I_{I}, \, \text{and} \, I_{O} \, \text{refer to I/O pins.} \, V_{IN} \, \text{refers to the control inputs.} \\ (2) & \text{All typical values are at} \, V_{DD} = 3.3 \, V \, (\text{unless otherwise noted}), \, T_{A} = 25^{\circ}\text{C}. \\ (3) & r_{on(flat)} \, \text{is the difference of } r_{on} \, \text{in a given channel at specified voltages.} \\ (4) & \Delta r_{on} \, \text{is the difference of } r_{on} \, \text{from center} \, (A_{4}, \, A_{5}) \, \text{ports to any other port.} \end{array}$

(4) Δr_{on} is the difference of r_{on} from center (A₄, A₅) ports to any other port. **Switching Characteristics** over recommended operating free-air temperature range, V_{DD} = 3.3 V ± 0.3 V, R_L = 200 Ω, C_L = 10 pF (unless otherwise noted) (see Figure 4 and Figure 5)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	TYP ⁽¹⁾	МАХ	UNIT
t _{pd} ⁽²⁾	A or B	B or A		0.04		ns
t _{PZH} , t _{PZL}	SEL	A or B	1.5		11.5	ns
t _{PHZ} , t _{PLZ}	SEL	A or B	1		8.5	ns
t _{sk(o)} ⁽³⁾	A or B	B or A		0.1	0.2	ns
t _{sk(p)} ⁽⁴⁾				0.1	0.2	ns

(1) All typical values are at $V_{DD} = 3.3 \text{ V}$ (unless otherwise noted), $T_A = 25^{\circ}C$. (2) The propagation delay is the calculated RC time constant of the typical ON-state resistance of the switch and the specified load capacitance when driven by an ideal voltage source (zero output impedance).

(3) Output skew between center port $(A_4 \text{ to } A_5)$ to any other port

(4) Skew between opposite transitions of the same output in a given device |t_{PHL}- t_{PLH}|

Dynamic Characteristics

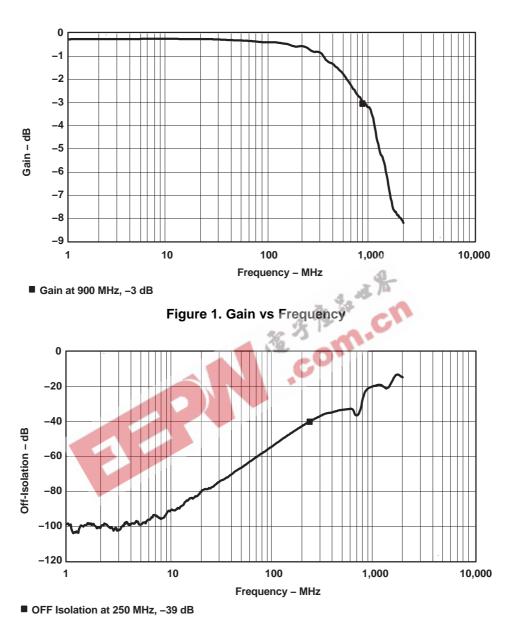
over recommended operating free-air temperature range, V_{DD} = 3.3 V \pm 0.3 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS					
X _{TALK}	R _L = 100 Ω,	f = 250 MHz,	See Figure 7	-	41	dB	
O _{IRR}	R _L = 100 Ω,	f = 250 MHz,	See Figure 8	-	39	dB	
BW	See Figure 6			ę	00	MHz	

(1) All typical values are at V_{DD} = 3.3 V (unless otherwise noted), T_A = 25°C.



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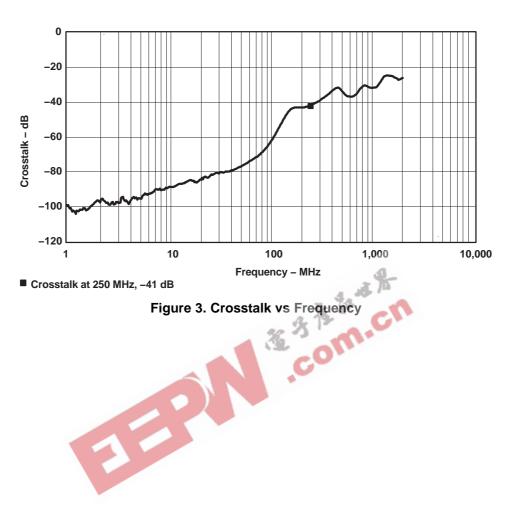


OPERATING CHARACTERISTICS

Figure 2. OFF Isolation vs Frequency



4-CHANNEL DIFFERENTIAL 8:16 MULTIPLEXER SWITCH FOR DVI/HDMI APPLICATIONS SCDS198C-OCTOBER 2005-REVISED MAY 2006



OPERATING CHARACTERISTICS (continued)

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1 2 48 TMDS Data 2 -0B1 TMDS Data 2 -2 47 TMDS Data 2+ 4 TMDS Data 2+ 1B₁ 9 45 0B₂ TMDS Data 1 -10 44 1B₂ TMDS Data 1+ 42 8 17 TMDS Data 1 A₂ 2B₁ TMDS Data 0 -18 10 41 TMDS Data 1+ TMDS Data 0+ 3B1 A₃ 39 23 2B₂ TMDS Clock+ 24 38 3B₂ TMDS Clock -15 35 TMDS Data 0 -A₄ 4**B**₄ DVI Connector 1 TMDS Data 0+ 17 34 5B1 (Single Link) A₅ 32 4B₂ 31 5B2 i Ē 21 29 TMDS Clock+ 6B4 A₆ -TMDS Clock 23 28 7B₁ A7 26 6B₂ 1 TMDS Data 2 -25 To DVI Receiver 2 7B₂ TMDS Data 2+ 9 ŝ 24 SEL TMDS Data 1 10 TMDS Data 1+ TS3DV416 E 17 TMDS Data 0 -18 TMDS Data 0+ 23 TMDS Clock+ 24 TMDS Clock -**DVI Connector Pin Assignments DVI Connector 2** Name Functio (Single Link) 1 TMDS Data 2 Digital red – (Link 1) TMDS Data 2+ Digital red + (Link 1) 2 TMDS Data 2/4 s 3 TMDS Data 4-Digital green – (Link 2) 4 Typical DVI Connector Digital green + (Link 2) 5 TMDS Data 4+ DDC clock 6 7 DDC data Analog Vertical Syn 8 9 TMDS Data 1-Digital green – (Link 1) 10 TMDS Data 1+ Digital green + (Link 1) 11 TMDS Data 1/3 shield TMDS Data 3-12 Digital blue – (Link 2) 13 TMDS Data 3+ Digital blue + (Link 2) 11 12 13 14 15 16 C5 10 14 +5V Power for monitor when in standby 20 21 22 23 24 C3 IC4 18 19 15 Groun Return for pin 14 and analog sync 16 Hot Plug Det 17 TMDS data 0 ital blue - (Link 1) and digital synd The TS3DV416 can be used to switch 18 TMDS data 0-Digital blue + (Link 1) and digital synd between two digital video ports. TMDS data 0/5 sh 19 20 TMDS data 5-Digital red – (Link 2) 21 TMDS data 5+ Digital red + (Link 2) 22 TMDS clock shield 23 TMDS clock+ Digital clock + (Links 1 and 2) 24 TMDS clock-Digital clock - (Links 1 and 2) C1 Analog Red C2 Analog Gree C3 Analog Blue C4

APPLICATION INFORMATION

Submit Documentation Feedback

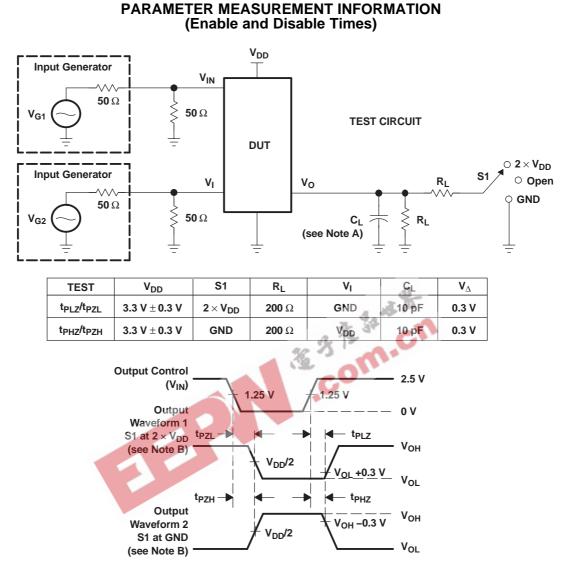
Return for R, G and B signals

Analog Horizontal Analog Ground

C5



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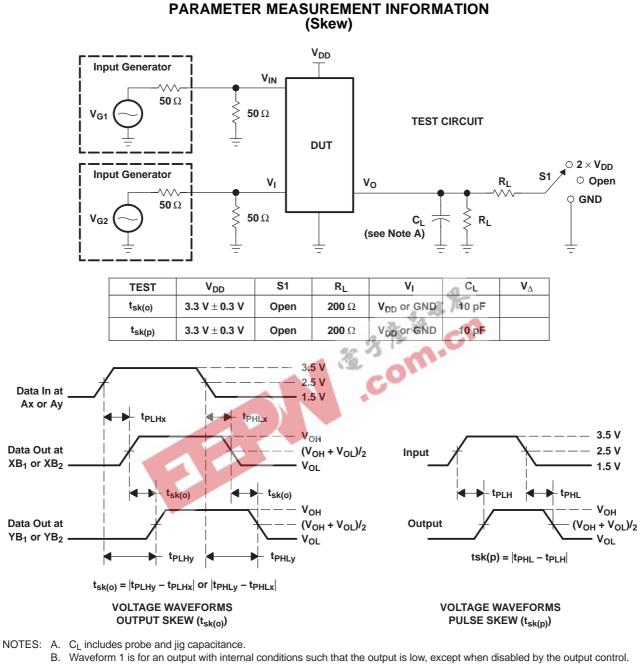


VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES

- NOTES: A. CL includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f \leq 2.5 ns. t_f \leq 2.5 ns.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en}.

Figure 4. Test Circuit and Voltage Waveforms

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D. Waverorm i is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.

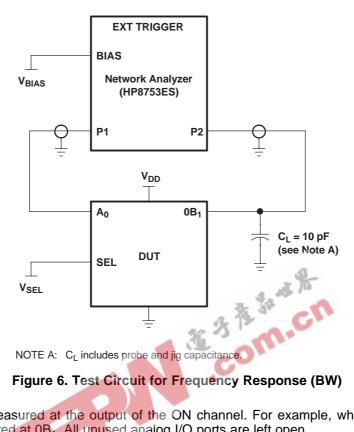
C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_r \leq 2.5 ns. t_f \leq 2.5 ns.

D. The outputs are measured one at a time, with one transition per measurement.

Figure 5. Test Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION



Frequency response is measured at the output of the ON channel. For example, when $V_{SEL} = 0$ and A_0 is the input, the output is measured at $0B_1$. All unused analog I/O ports are left open.

HP8753ES Setup

Average = 4 RBW = 3 kHz

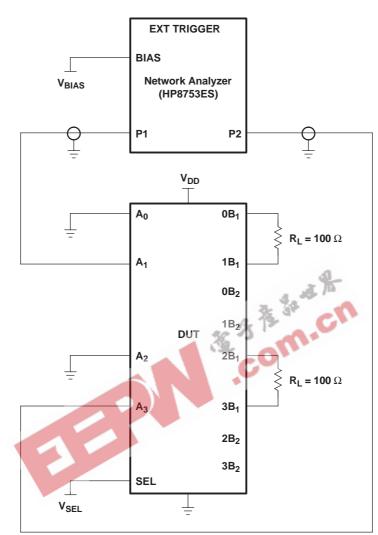
V_{BIAS} = 0.35 V

ST = 2 s

P1 = 0 dBM



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. C_L includes probe and jig capacitance. B. A 50- Ω termination resistor is needed to match the loading of the network analyzer.

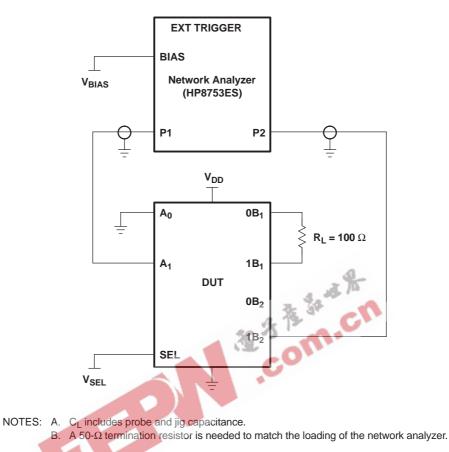
Figure 7. Test Circuit for Crosstalk (X_{TALK})

Crosstalk is measured at the output of the nonadjacent ON channel. For example, when $V_{SEL} = 0$ and A_1 is the input, the output is measured at A_3 . All unused analog input (A) ports are connected to GND, and output (B) ports are left open.

HP8753ES Setup

Average = 4 RBW = 3 kHz $V_{BIAS} = 0.35 V$ ST = 2 s P1 = 0 dBM





PARAMETER MEASUREMENT INFORMATION

OFF isolation is measured at the output of the OFF channel. For example, when $V_{SEL} = GND$ and A_1 is the input, the output is measured at $1B_2$. All unused analog input (A) ports are connected to ground, and output (B) ports are left open.

Figure 8. Test Circuit for OFF Isolation (O_{IRR})

HP8753ES Setup

Average = 4 RBW = 3 kHz V_{BIAS} = 0.35 V

ST = 2 s

P1 = 0 dBM

27-Sep-2007

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TS3DV416DGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TS3DV416DGGRE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TS3DV416DGGRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TS3DV416DGVR	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TS3DV416DGVRG4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available. 59

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/product content for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

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Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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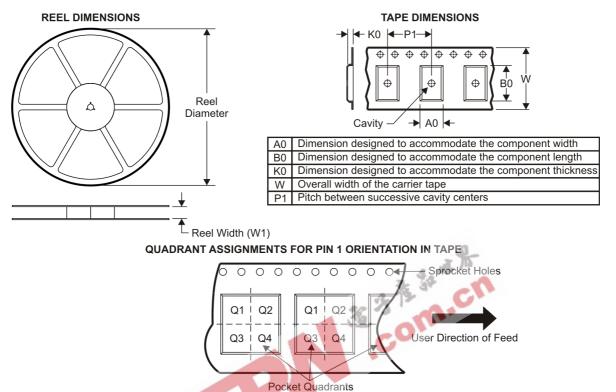
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PACKAGE MATERIALS INFORMATION

11-Mar-2008

TAPE AND REEL INFORMATION

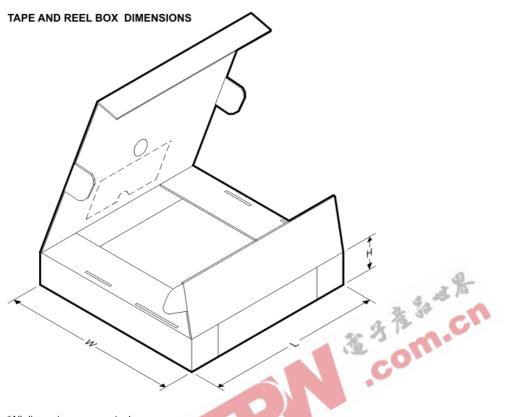


Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadra
TS3DV416DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	15.8	1.8	12.0	24.0	Q1
TS3DV416DGVR	TVSOP	DGV	48	2000	330.0	24.4	6.8	10.1	1.6	12.0	24.0	Q1



PACKAGE MATERIALS INFORMATION

11-Mar-2008



*All dimensions are nominal

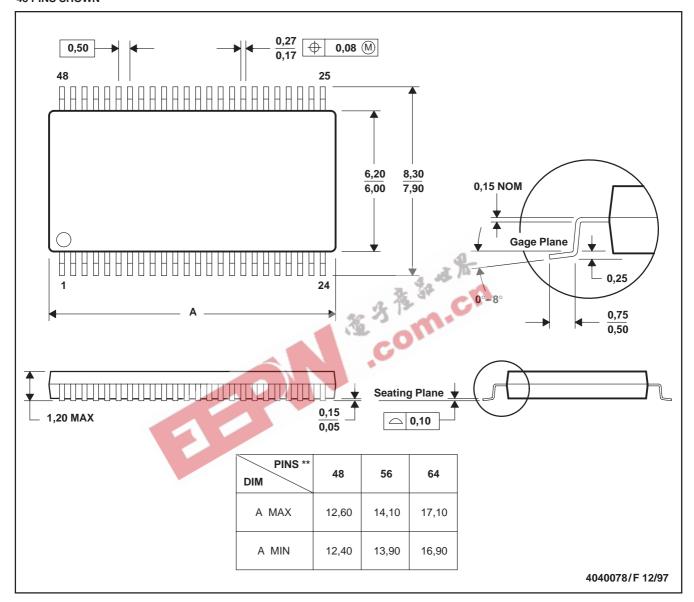
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TS3DV416DGGR	TSSOP	DGG	48	2000	346.0	346.0	41.0
TS3DV416DGVR	TVSOP	DGV	48	2000	346.0	346.0	41.0

MECHANICAL DATA

MTSS003D - JANUARY 1995 - REVISED JANUARY 1998

PLASTIC SMALL-OUTLINE PACKAGE

DGG (R-PDSO-G**) 48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153



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